



Material Content Data Sheet



Sales Product Name				IPS80R750P7		Issued		25. January 2018	
MA#				MA001662420					
Package				PG-TO251-3-344		Weight*		334.63 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.170	0.65	0.65	6485	6485	
leadframe	inorganic material	phosphorus	7723-14-0	0.046	0.01		138		
	non noble metal	iron	7439-89-6	0.154	0.05		461		
	non noble metal	copper	7440-50-8	154.154	46.07	46.13	460670	461269	
	non noble metal	aluminium	7429-90-5	0.470	0.14	0.14	1405	1405	
wire	non noble metal	aluminium	7429-90-5	0.470	0.14	0.14	1405	1405	
encapsulation	organic material	carbon black	1333-86-4	0.443	0.13		1325		
	plastics	epoxy resin	-	13.452	4.02		40198		
	inorganic material	silicondioxide	60676-86-0	133.924	40.02	44.17	400215	441738	
leadfinish	non noble metal	tin	7440-31-5	4.142	1.24	1.24	12378	12378	
plating	non noble metal	nickel	7440-02-0	0.607	0.18	0.18	1813	1813	
solder	non noble metal	tin	7440-31-5	0.043	0.01		130		
	noble metal	silver	7440-22-4	0.054	0.02		162		
	non noble metal	lead	7439-92-1	2.073	0.62	0.65	6196	6488	
heatspreader	inorganic material	phosphorus	7723-14-0	0.007	0.00		21		
	non noble metal	iron	7439-89-6	0.023	0.01		68		
	non noble metal	copper	7440-50-8	22.867	6.83	6.84	68335	68424	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com